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U.S. UTILITY Patent Application

PATENT NUMBER and  
ISSUE DATE

APPL NUM 10090142	FILING DATE 03/05/2002	CLASS 219	SUBCLASS 180.21	GAU 1725	EXAMINER EDMONDSON
<b>**APPLICANTS:</b> Miyazawa Ikuya;					
<b>**CONTINUING DATA VERIFIED:</b> <i>None - CRE</i>					
<b>** FOREIGN APPLICATIONS VERIFIED:</b> JAPAN 2001-75534 03/16/2001 - <i>CRE</i>					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input checked="" type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no Verified and Acknowledged Examiners's initials				ATTORNEY DOCKET NO 112155	
TITLE : Soldering method, soldering device, and method and device of fabricating electronic circuit module					

U.S. DEPT. OF COMM./PAT. & TM-PTO-436L (Rev. 12-94)

<b>NOTICE OF ALLOWANCE MAILED</b>		<b>CLAIMS ALLOWED</b>	
		Total Claims	Print Claim for O.G.
<b>ISSUE FEE</b>		<b>DRAWING</b>	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
		Print Fig.	
<input type="checkbox"/> <b>TERMINAL DISCLAIMER</b>		<b>Application Examiner</b>	
		<b>PREPARED FOR ISSUE</b>	
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